News Release

UTAC starts full turnkey production for Infineon Technologies' Mobile-RAM with its D2wCSP package solution

- Full turnkey support for Mobile-RAM assembled in UTAC's D2wCSP package solution
- D2wCSP enables two Mobile-RAMs within a single package instead of two
- UTAC's D2wCSP enables doubling of memory density without increase in package size especially critical to space constrained applications

Singapore – 15 February 2005 – United Test and Assembly Center Ltd ("UTAC") a leader in semiconductor assembly and test services, has commenced full turnkey production for Infineon Technologies' Mobile-RAM assembled in D2wCSP.

Infineon Technologies (FSE/NYSE: IFX) is the fourth largest semiconductor company worldwide (source: Gartner, Dec 2004) and one of the world's leading DRAM suppliers. Infineon's Mobile-RAM is a family of very low power DRAM that can reduce power consumption by up to 80% compared to a standard SDRAM of the same density. The power efficient Mobile-RAM is targeted at mobile and wireless applications such as PDAs, smart and feature cell phones, digital cameras and MP3 players. Demand for high-end smart phones which typically feature PDA and digital camera functions is expected to grow at 51.6% on a compounded annual basis between 2004 through 2008 (source: Gartner, December 2004).

UTAC's D2wCSP is a 3-D packaging solution that packs two Mobile-RAMs into a single package, doubling memory density without increasing package size. This is critical to memory demanding, space-constrained applications such as smart phones and MP3 players. D2wCSP is available as an environmentally friendly “Green” package solution and is the only 512Mb Mobile-RAM in a single package in the market.

“We are very pleased to start turnkey production for Infineon’s Mobile-RAM using our D2wCSP solution,” said Ms. June Chia, Executive Vice President at UTAC. “There is great growth potential for this product with strong market demand for such small and yet high-capacity memory solutions that would dramatically reduce component footprint in mobile devices. This is core to our Broadband, Mobile and Wireless (BM/W) strategy.”

“UTAC is a proven leader in providing innovative packaging and comprehensive test solutions,” said Mr. Gunnar Becker, Senior Director for Backend Operations and Subcon Management at Infineon’s Memory Products business group “We highly appreciate UTAC’s innovative D2wCSP solution as it opens up new growth opportunities for our high-growth Mobile-RAM products.”

Note: wCSP® is a UTAC registered trademark; MP3 = MPEG Layer 3

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About United Test and Assembly Center Ltd (UTAC)

UTAC, listed on the Main Board of Singapore Exchange, is a leading independent provider of total semiconductor test and assembly solution to its customers, which comprise Integrated Device Manufacturers ("IDMs"), fabless companies and wafer foundries. The company provides wafer probing and final testing services on a diverse selection of test platforms for a range of semiconductors including memory, logic, mixed-signal and radio frequency ICs. Besides testing services, UTAC also provides assembly services for a broad range of leadframe and array packages.

In addition to its manufacturing and engineering operations in Singapore and Shanghai, China, UTAC also has an established global network of sales offices in the United States, Europe, China and Japan. For more information, visit www.utac.com.sg.

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